

## Product / Process Change Notice

**Devices affected:**

Chip processes CP191V and CP591X, NPN and PNP wafers and die in chip form.

**Extent of change:**

Wafer diameter has changed from 5" to 6". In order to optimize the die attach process, a slight adjustment was also made in the backside metallization thickness (see Table # 1).

**Reason for change:**

Wafer foundry process change.

**Effect of change:**

This change does not affect the form, fit, or function of any device; however, gross die quantities per wafer have increased.

**Qualification data:**

Standard evaluation and qualifications were completed resulting in no performance differences compared to current product.

**Earliest effective date of change:**

Existing inventory of 5" wafers will be shipped until depleted.

**Table 1**

	CP191V Before Change	CP191V After Change		CP591X Before Change	CP591X After Change
Die Size	16.5 x 16.5 MILS	16.5 x 16.5 MILS		19.3 x 19.3 MILS	19.3 x 19.3 MILS
Die Thickness	7.1 MILS	7.1 MILS		5.9 MILS	5.9 MILS
Base Bonding Pad Size	3.5 x 4.3 MILS	3.5 x 4.3 MILS		3.5 x 4.3 MILS	3.5 x 4.3 MILS
Emitter Bonding Pad Size	3.5 x 4.3 MILS	3.5 x 4.3 MILS		3.5 x 4.5 MILS	3.5 x 4.5 MILS
Top Side Metalization	Al – 13,000Å	Al – 13,000Å		Al – 13,000Å	Al – 13,000Å
Back Side Metalization	Au-As – 9,000Å	Au-As – 12,000Å		Au-As – 9,000Å	Au-As – 12,000Å
Scribe Alley Width	1.96 MILS	1.96 MILS		1.75 MILS	1.75 MILS
Wafer Diameter	5 INCHES	6 INCHES		5 INCHES	6 INCHES
Gross Die Per Wafer	62,510	87,691		45,900	64,286



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<http://www.centrasemi.com/processchange>

**PCN # 260**

**Final Notification Date:**

**August 1, 2025**

**Part Numbers Affected:**

<b>CP191V Process</b>	<b>CP591X Process</b>
CP191V-CEN1256-CT	CP591X-CEN1216-CT
CP191V-2N2219A-CT	CP591X-CEN1216-WN
CP191V-2N2219A-WN	CP591X-CEN1347-WF
CP191V-2N2222A-CM	CP591X-CEN197-CM200
CP191V-2N2222A-CT	CP591X-2N2905-CM
CP191V-2N2222A-CTO	CP591X-2N2905-CT
CP191V-2N2222A-CT20	CP591X-2N2905-WN
CP191V-2N2222A-WM	CP591X-2N2905A-CM
CP191V-2N2222A-WN	CP591X-2N2905A-CT
CP191V-2N2222A-WR	CP591X-2N2905A-WN
CP191V-2N2645-CT	CP591X-2N2907A-CM
CP191V-2N2645-WN	CP591X-2N2907A-CT
CP191V-2N4401-CT	CP591X-2N2907A-CT20
CP191V-2N4401-WN	CP591X-2N2907A-WN
CP191V-2222A-WS105	CP591X-2907A-WS105

**Additional Qualification data:**

Contact your local Central Semiconductor sales representative. As per JEDEC standard JESD46, Customer Notification of Product/Process Changes by Solid-State Suppliers, a lack of acknowledgement of a PCN within thirty (30) days constitutes acceptance of the change. For any questions concerning this notification, please contact your local sales representative.

**Customer Acknowledgement:**

The undersigned acknowledges and accepts Central Semiconductor's Product/Process Change Notification (PCN).

Company Name:	
Address:	
Printed Name:	
Title:	
Signature:	
Date:	